

determining oxygen content in exhaust gases of an internal combustion engine, comprising the steps of:

sintering at least one ceramic paste present in film form to yield the sensing element; and

blunting edges of the sensing element before sintering to increase a thermal shock resistance of the sensing element.

14. (New) The method according to claim 13, wherein the step of blunting includes the step of blunting the edges of the sensing element by shaping.

15. (New) The method according to claim 14, wherein the step of blunting the edges of the sensing element further includes the step of blunting the edges of the sensing element by stamping.

16. (New) The method according to claim 13, further comprising the step of:

introducing a profile into a stamping apparatus for pre-pressing a laminate construction of unsintered films of the sensing element.

17. (New) The method according to claim 16, further comprising the step of:

obtaining the profile by introducing a profiling film into the stamping apparatus.

18. (New) The method according to claim 17, wherein the step of blunting further includes the step of obtaining the profile by introducing profiling film having an anti-adhesion coating into the stamping apparatus.

19. (New) The method according to claim 13, wherein the step of blunting the edges of the sensing element further includes the step of blunting the edges of the sensing element using a laser treatment.

20. (New) The method according to claim 13, wherein the step of blunting includes the step of blunting the edges of the sensing element using an excimer laser having definable masking.

21. (New) The method according to claim 13, wherein the step of blunting includes the step of treating sectioned sensing elements with a laser, the sectioned sensing elements having a composition construction of green films.

22. (New) The method according to claim 21, further comprising the step of:

sectioning the sensing element from a wafer, the wafer including the sectioned sensing elements, wherein the treating step is performed prior to the sectioning step.

23. (New) The method according to claim 13, further comprising the step of:

sectioning the sensor element from a wafer with a laser, the wafer including individual sensing elements composed of a composite of green films, wherein the sectioning step is performed simultaneously with the blunting step, and wherein the blunting step includes the step of blunting the edges of the sensing element with the laser.

24. (New) The method according to claim 13, wherein the step of blunting further includes the step of producing a chamfer on the edges having at least one of a convex surface, a concave surface and a flat surface.

Remarks

This Preliminary Amendment cancels, without prejudice, claims 1-12 in the underlying PCT Application No. PCT/DE98/00525, and adds new claims 13-24. The new claims conform the claims to U.S. Patent and Trademark Office rules